

09/331763

510 Rec'd PCT/PTO 25 JUN 1999

4/Pre A

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of :
Kazuto NISHIDA :
Serial No. [Not yet assigned] :
Filed June 25, 1999 : Attn: BOX PCT
Corresponding to PCT/JP97/04873 : Docket No. 177/526327
Filed December 26, 1997 :
METHOD AND APPARATUS FOR :
MOUNTING ELECTRONIC COMPONENT :
ON CIRCUIT BOARD :

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents,
Washington, D.C.

Sir:

Kindly amend the above-identified application as follows.

IN THE CLAIMS:

Claims 1-31, rewrite as follows:

Subf 2
a1

1. (Amended) An electronic component mounting method comprising:
aligning in position electrodes [(5)] of a circuit board [(4)] with bumps [(3)] formed by wire-bonding on electrodes [(2)] of an electronic component [(1)] with interposition of an insulative thermosetting resin [(6, 6b)] that includes no conductive particle; and
hardening with heat the thermosetting resin interposed

ATTACHMENT E